

General Description

The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS® Z series is integrated with fast recovery diode (FRD) to minimize reverse recovery time. It is suitable for resonant switching topologies to reach higher efficiency, higher reliability and smaller form factor.

Features

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent stability and uniformity



Applications

- LED lighting
- Telecom
- Adapter
- Server
- Solar/UPS

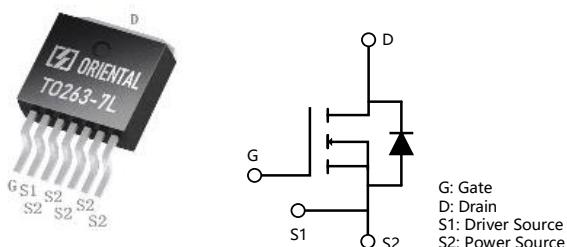
Key Performance Parameters

Parameter	Value	Unit
V_{DS}	600	V
I_D , pulse	156	A
$R_{DS(ON)}$, max @ $V_{GS}=10V$	45	mΩ
Q_g	87	nC
PD	280	W

Marking Information

Product Name	Package	Marking
OSG60R045K7T3ZF	TO263-7L	OSG60R045K7T3Z

Package & Pin Information



Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	600	V
Gate source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾ , $T_C=25\text{ }^\circ\text{C}$	I_D	52	A
Continuous drain current ¹⁾ , $T_C=100\text{ }^\circ\text{C}$		32.8	
Pulsed drain current ²⁾ , $T_C=25\text{ }^\circ\text{C}$	$I_{D,\text{pulse}}$	156	A
Continuous diode forward current ¹⁾ , $T_C=25\text{ }^\circ\text{C}$	I_S	52	A
Diode pulsed current ²⁾ , $T_C=25\text{ }^\circ\text{C}$	$I_{S,\text{pulse}}$	156	A
Power dissipation ³⁾ , $T_C=25\text{ }^\circ\text{C}$	P_D	280	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	486	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\text{...}480\text{ V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0\text{...}480\text{ V}$, $I_{SD}\leq I_D$	dv/dt	50	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	0.45	$^\circ\text{C/W}$
Thermal resistance, junction-ambient ⁴⁾	$R_{\theta JA}$	62	$^\circ\text{C/W}$

Electrical Characteristics at $T_j=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	600			V	$V_{GS}=0\text{ V}$, $I_D=1\text{ mA}$
Gate threshold voltage	$V_{GS(\text{th})}$	3.5		5.5	V	$V_{DS}=V_{GS}$, $I_D=1\text{ mA}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		43.2	45	$\text{m}\Omega$	$V_{GS}=10\text{ V}$, $I_D=26\text{ A}$
			107.3			$V_{GS}=10\text{ V}$, $I_D=26\text{ A}$, $T_j=150\text{ }^\circ\text{C}$
Gate-source leakage current	I_{GS}			100	nA	$V_{GS}=30\text{ V}$, $V_{DS}=0\text{ V}$
				-100		$V_{GS}=-30\text{ V}$, $V_{DS}=0\text{ V}$
Drain-source leakage current	I_{DS}			10	μA	$V_{DS}=650\text{ V}$, $V_{GS}=0\text{ V}$
Gate resistance	R_G		2.8		Ω	$f=1\text{ MHz}$, Open drain

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{iss}		4153		pF	V _{GS} =0 V, V _{DS} =50 V, f=100 kHz
Output capacitance	C _{oss}		250		pF	
Reverse transfer capacitance	C _{rss}		5.2		pF	
Effective output capacitance, energy related	C _{o(er)}		160		pF	V _{GS} =0 V, V _{DS} =0 V-400 V
Effective output capacitance, time related	C _{o(tr)}		880		pF	
Turn-on delay time	t _{d(on)}		29		ns	V _{GS} =10 V, V _{DS} =400 V, R _G =2 Ω, I _D =20 A
Rise time	t _r		9		ns	
Turn-off delay time	t _{d(off)}		64		ns	
Fall time	t _f		3		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q _g		87		nC	V _{GS} =10 V, V _{DS} =400 V, I _D =20 A
Gate-source charge	Q _{gs}		26		nC	
Gate-drain charge	Q _{gd}		36		nC	
Gate plateau voltage	V _{plateau}		7.1		V	

Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V _{SD}			1.3	V	I _S =52 A, V _{GS} =0 V
Reverse recovery time	t _{rr}		162		ns	
Reverse recovery charge	Q _{rr}		944		nC	
Peak reverse recovery current	I _{rrm}		10.4		A	

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
- 5) V_{DD}=100 V, V_{GS}=10 V, L=80 mH, starting T_j=25 °C.

Electrical Characteristics Diagrams

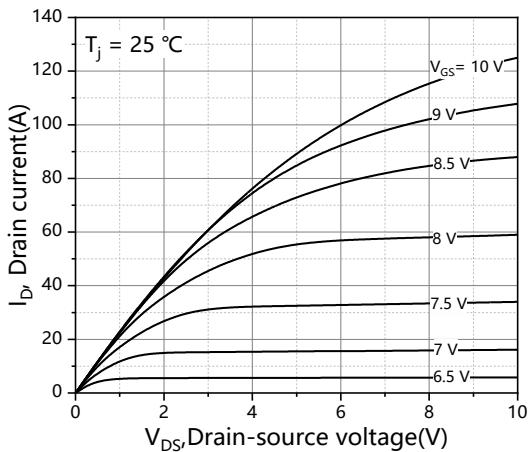


Figure 1. Typ. output characteristics $T_j=25^\circ\text{C}$

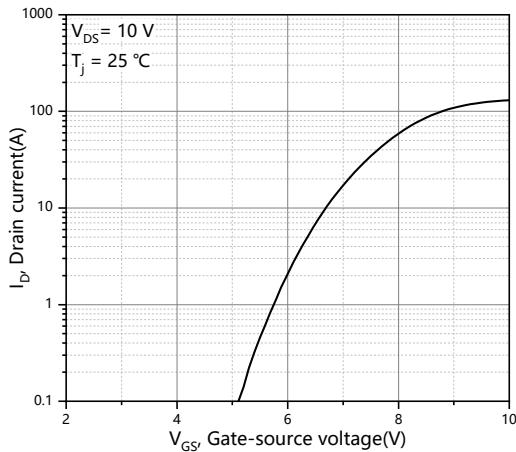


Figure 2. Typ. transfer characteristics

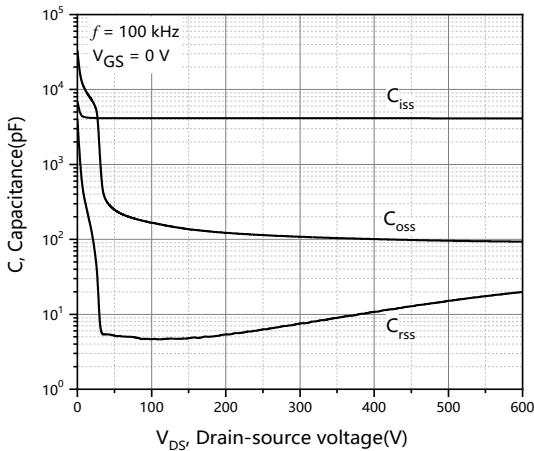


Figure 3. Typ. capacitances

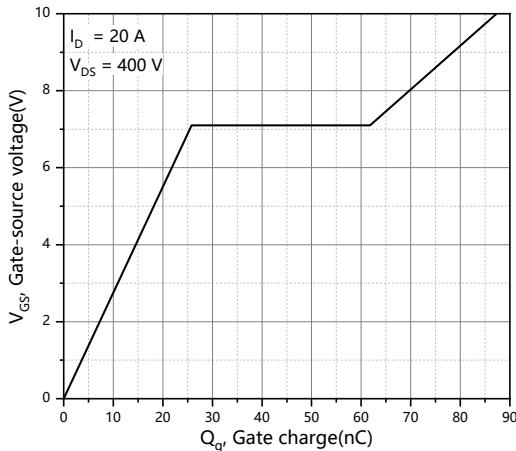


Figure 4. Typ. gate charge

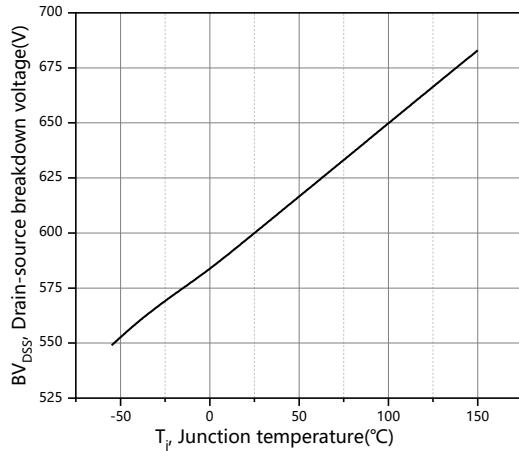


Figure 5. Drain-source breakdown voltage

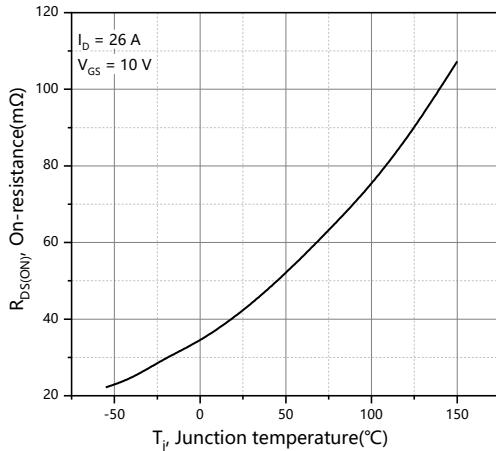
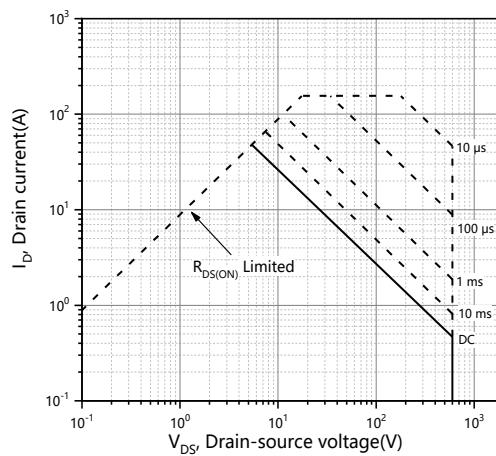
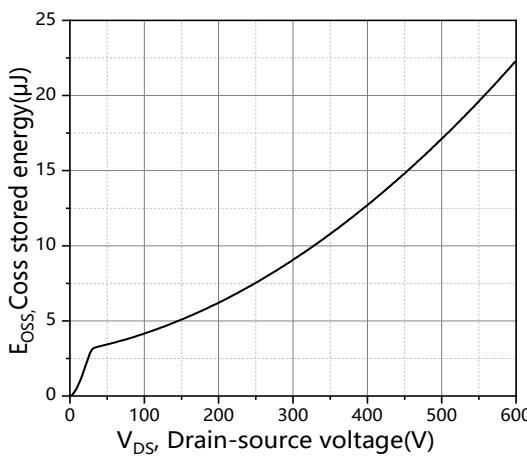
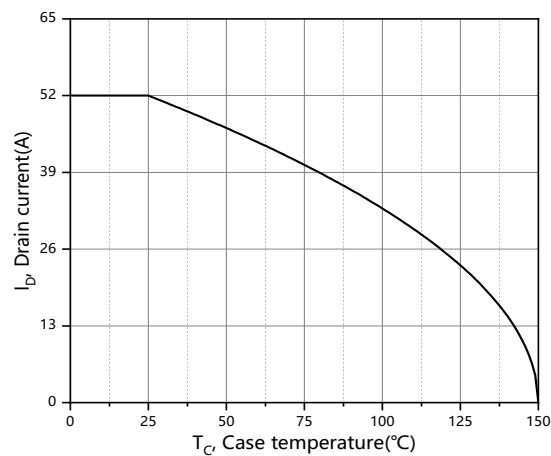
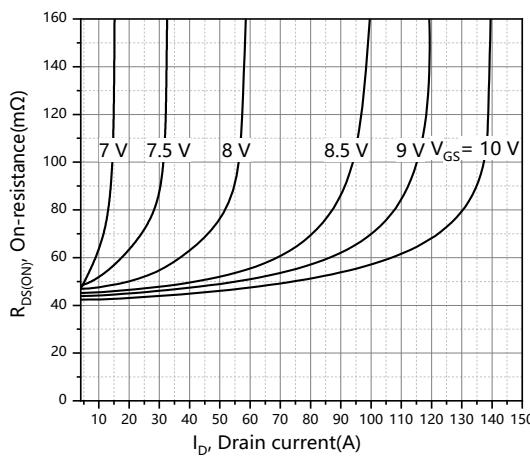
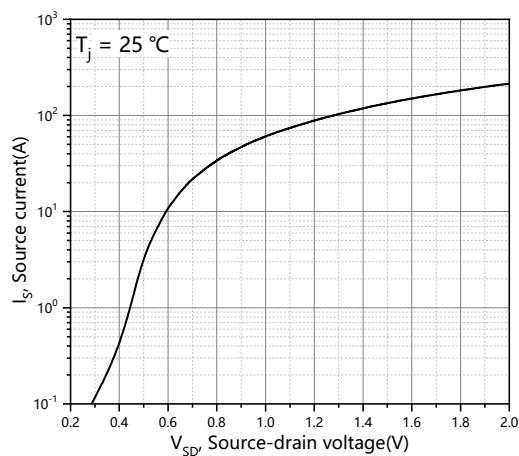
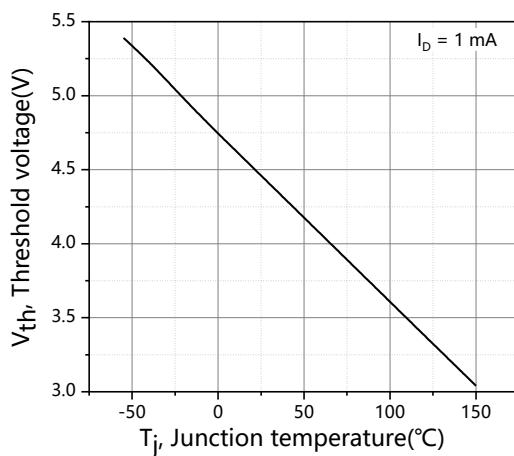


Figure 6. Drain-source on-state resistance



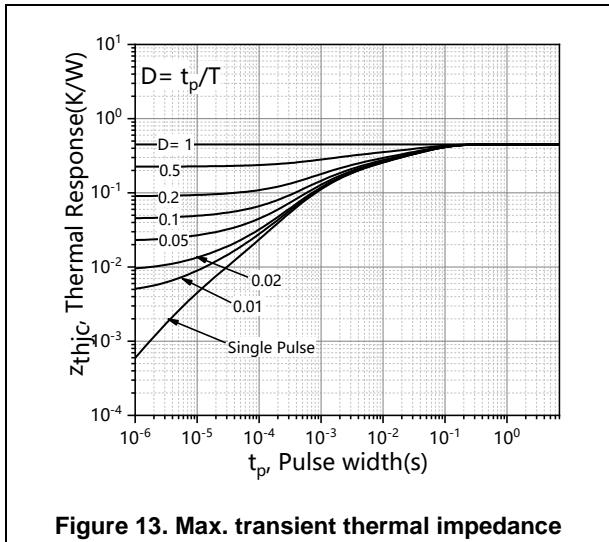


Figure 13. Max. transient thermal impedance

Test circuits and waveforms

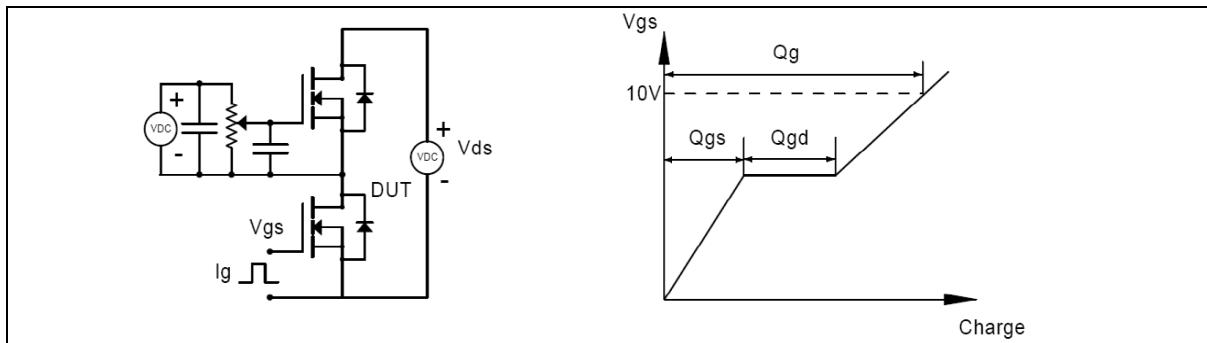


Figure 1. Gate charge test circuit & waveform

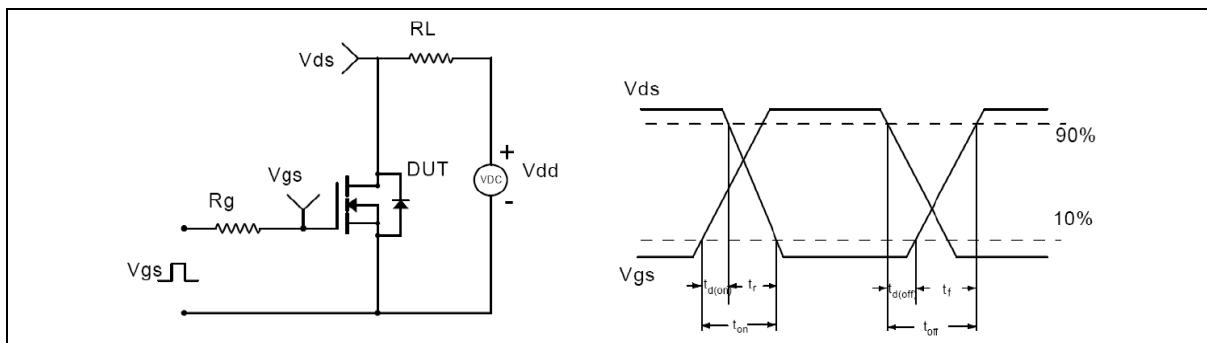


Figure 2. Switching time test circuit & waveforms

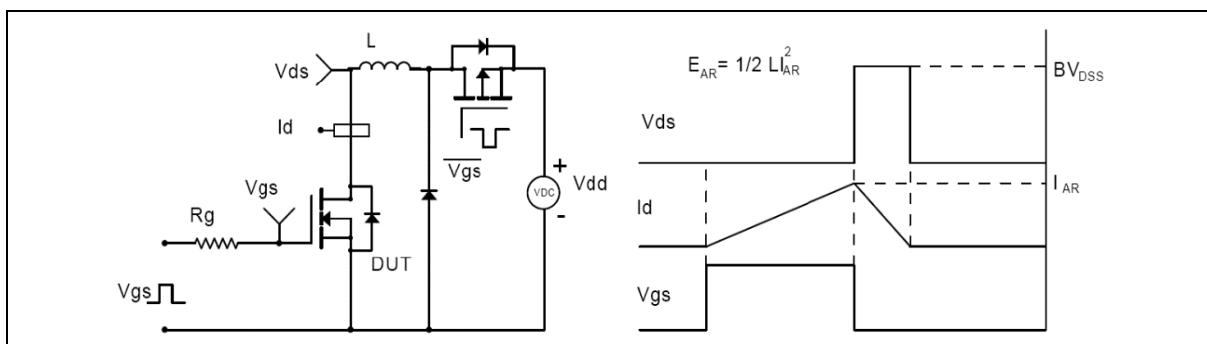


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

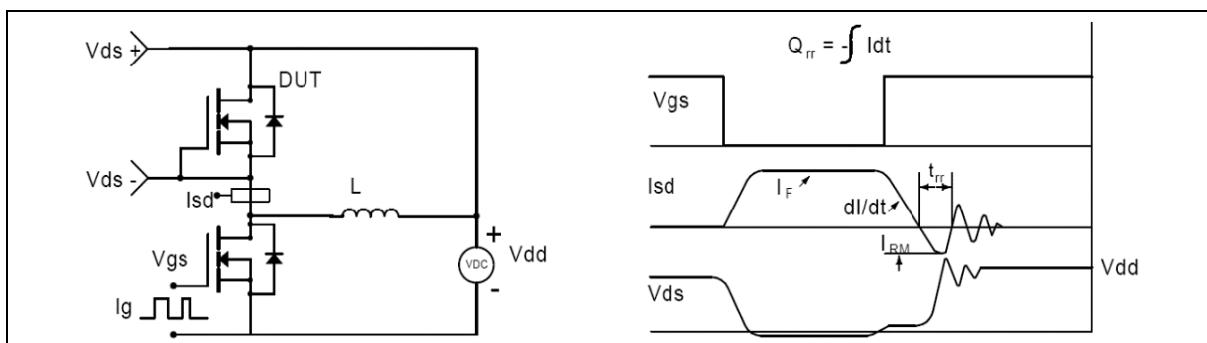
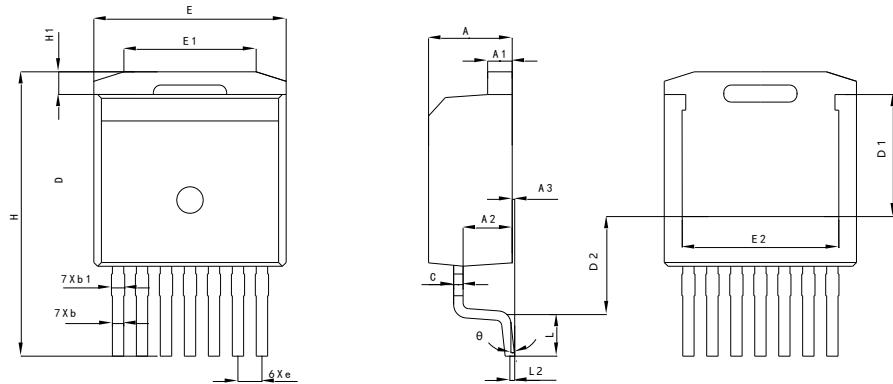


Figure 4. Diode reverse recovery test circuit & waveforms

Package Information



Symbol	mm		
	Min	Nom	Max
A	4.30	4.43	4.56
A1	1.20	1.30	1.40
A2	2.45	2.60	2.75
A3	0.00	0.13	0.25
b	0.50	0.60	0.70
b1	0.60	0.70	0.90
c	0.45	0.50	0.60
D	8.93	9.08	9.23
D1	6.30	6.45	6.60
D2	5.18 REF		
e	1.27 BSC		
E	10.08	10.18	10.28
E1	7.00 REF		
E2	7.90	8.30	8.70
H	14.53	15.03	15.53
H1	0.98	1.20	1.42
L	1.90	2.20	2.50
L2	0.25 BSC		
θ	0°	3°	7°

Veision: TO263-7L-P package outline dimension

Ordering Information

Package Type	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO263-7L-P	800	1	800	5	4000

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG60R045K7T3ZF	TO263-7L	yes	yes	yes

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